



Material Content Data Sheet



Sales Product Name		BFP 520F H6327		Issued		20. April 2015			
MA#		MA001351310							
Package		PG-TSFP-4-1		Weight*		1.87 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	non noble metal	tin	7440-31-5	0.001	0.03		269		
	noble metal	gold	7440-57-5	0.002	0.10		1041		
	inorganic material	silicon	7440-21-3	0.014	0.77	0.90	7715	9025	
leadframe	inorganic material	silicon	7440-21-3	0.000	0.01		79		
	non noble metal	titanium	7440-32-6	0.001	0.04		395		
	non noble metal	chromium	7440-47-3	0.002	0.12		1184		
	non noble metal	copper	7440-50-8	0.734	39.30	39.47	393028	394686	
wire	noble metal	gold	7440-57-5	0.007	0.35	0.35	3543	3543	
encapsulation	organic material	carbon black	1333-86-4	0.010	0.52		5180		
	plastics	epoxy resin	-	0.208	11.14		111376		
	inorganic material	silicondioxide	60676-86-0	0.750	40.15	51.81	401472	518028	
leadfinish	non noble metal	tin	7440-31-5	0.050	2.65	2.65	26527	26527	
plating	noble metal	silver	7440-22-4	0.090	4.82	4.82	48191	48191	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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